

/ Descriptions

/ Features

/ Applications

DC/DC

/ Equivalent Circuit



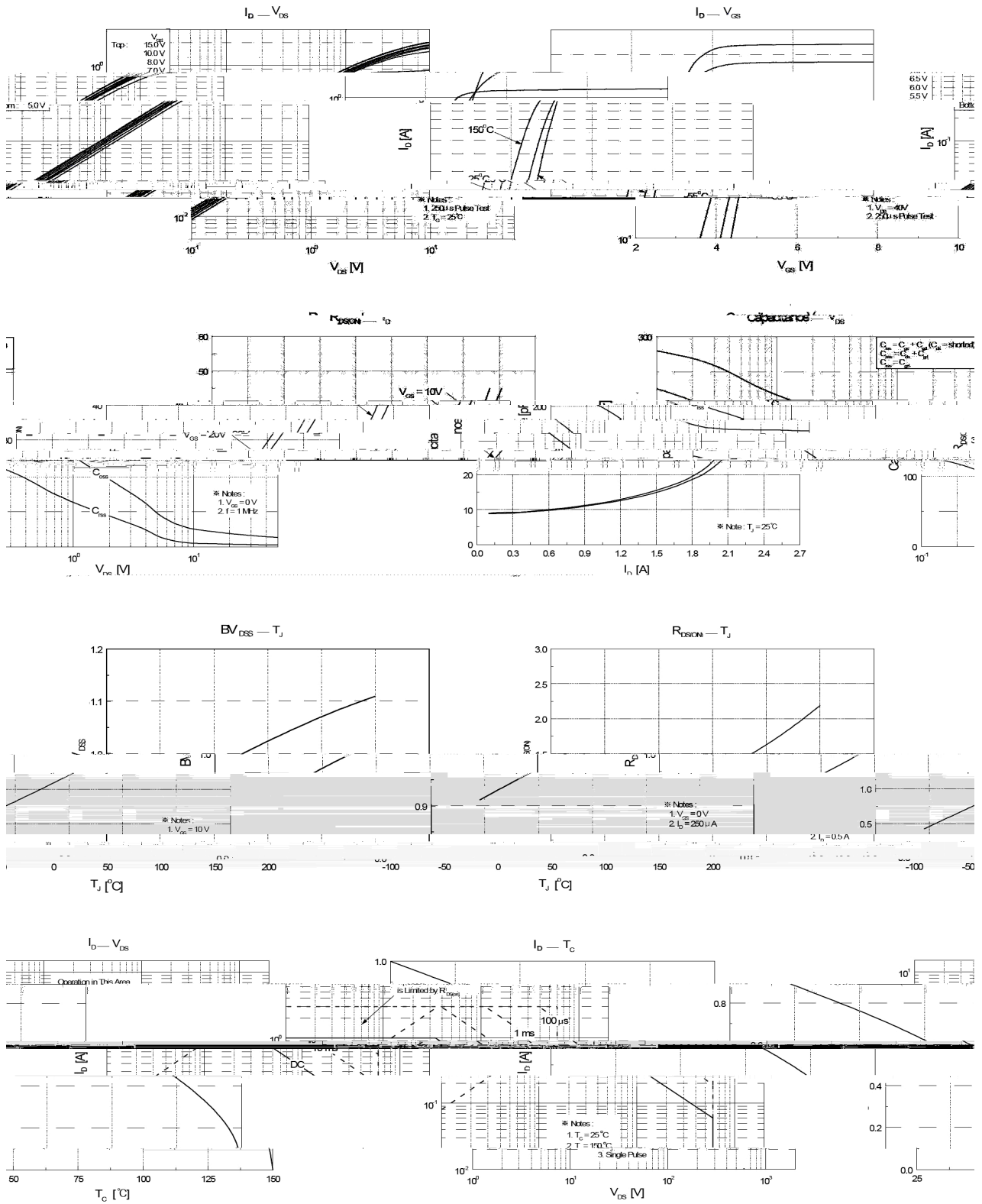
/ Pinning



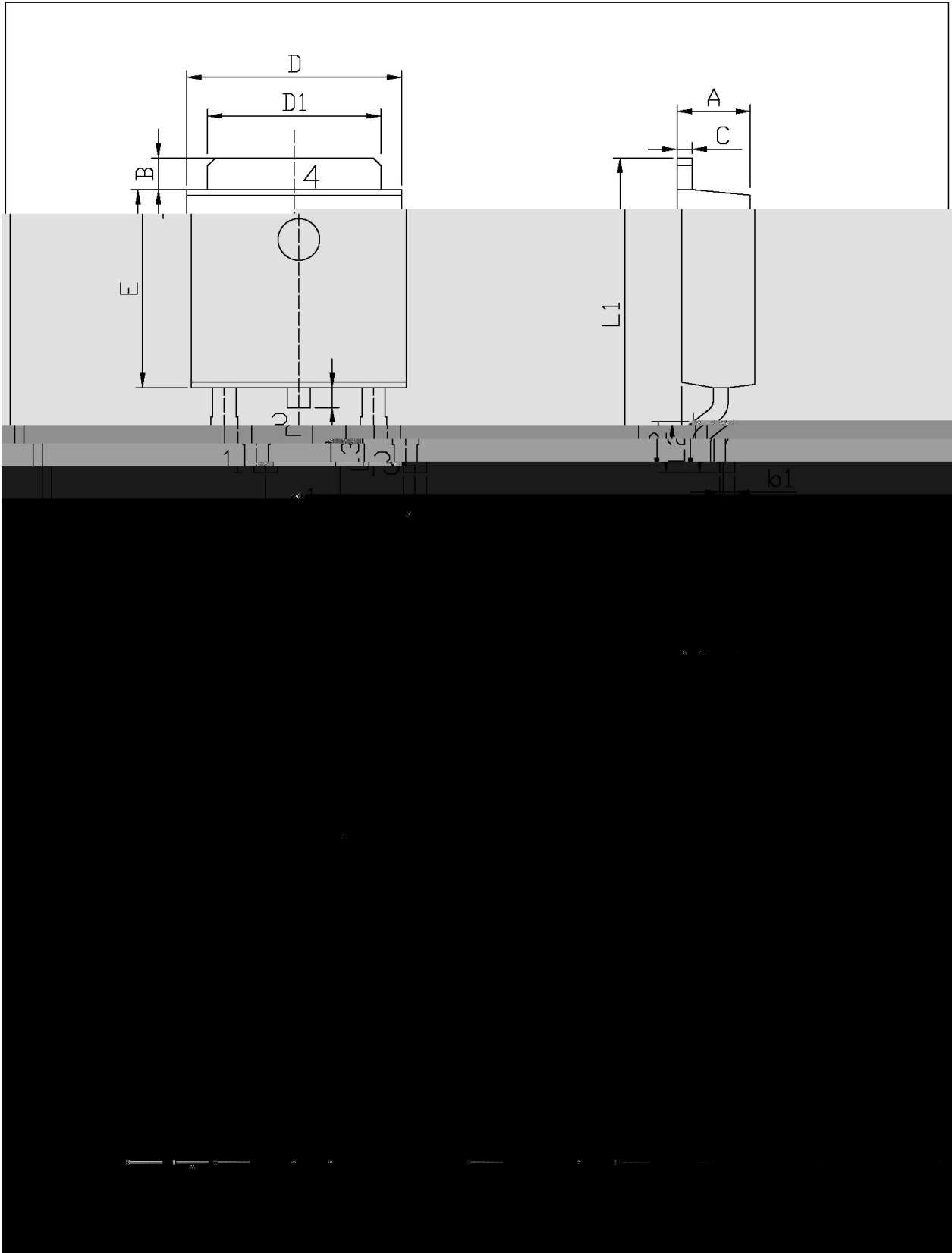
/ h_{FE} Classifications & Marking

		μ				
						μ
						μ
						μ

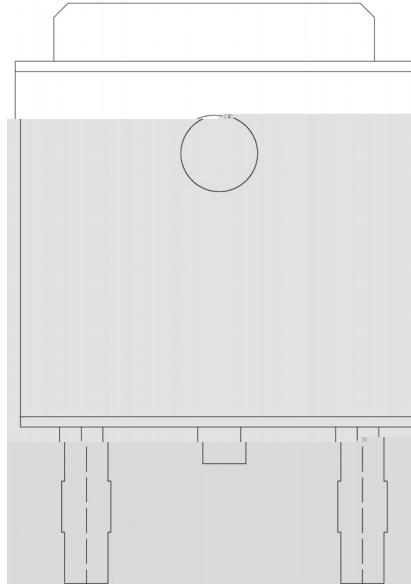
/ Electrical Characteristic Curve



/ Package Dimensions

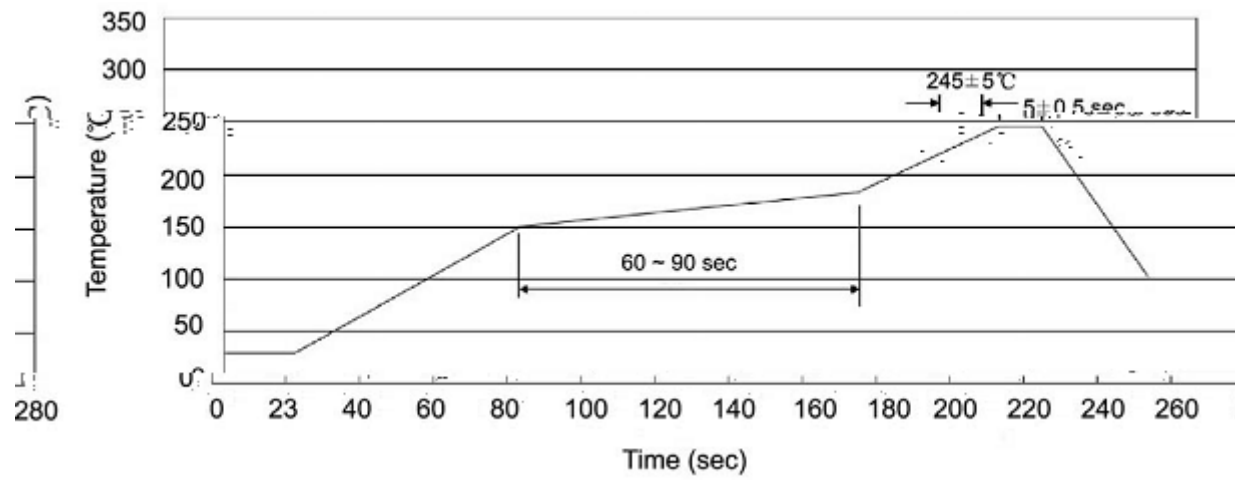


/ Marking Instructions



1N60

() / Temperature Profile for IR Reflow Soldering(Pb-Free)



± ± ± ±

/ Resistance to Soldering Heat Test Conditions

± ±

/ Packaging SPEC.

封装形式	包装数量					包装尺寸		
	只 卷盘	卷盘 盒	只 盒	盒 箱	只 箱		盒	箱